Flex PCBs

Technical Specification		
Number Of Layer		Flexible 1~8
Material		PI PET FR-4 BT
Copper Thickness		1/3oz 1/2oz 1oz max 2oz
Min Board thickness		2mil
Max. Board Thickness		126mil
Max Panel Size		18 X 24inch (460mm x 616mm)
Min. Trace Wide & Line Space	Single Sided	2mil / 2mil
	Double Sided	3mil / 3mil
	4 Layers	3mil / 3mil
	6 Layers	3mil / 3mil
	8 Layers	3mil / 3mil
Min. Hole Diameter	Drilling /shadow	Φ0.05mm(2mil)
	Punching	Φ0.30mm(12mil)
Dimension Tolerance	Hole Position	±0.050 (2 mil)
	Conductor Width (W)	±10%
	Hole Diameter (H)	±0.03 mm (1.2 mil)
		[With PTH ±0.05 mm (2 mil)]
	Outline Dimension	±0.10 mm (4 mil)
	Conductors & Outline	±0.10 mm (4 mil)
	(C-O)	
Surface Treatment On Land Area		Flash Gold/ Immersion Gold/ Pure Tin Plating/Entek
Insulation Resistance		10KΩ~20MΩ(typical:5MΩ)
Coverlay Continuity		1.08KG/cm2
Test voltage		300V(max)
	0.30-1.60	0.10mm (4mil)
	1.61-6.50	0.15mm (6mil)
Minimum spacing between hole edge to circuitry pattern		PTH hole: 0.13mm (5mil)
		NPTH hole: 0.18mm (7mil)
Image transfer Registration tolerance	Circuit pattern vs. index hole	±0.075 (3mil)
	Circuit pattern vs. 2nd drill hole	±0.075 (3mil)
Registration tolerance of front/back image	Front image vs. back image	0.05mm (2mil)
Multilayer	Layer-layer misregistration	4layers:0.05mm (2mil) max.
		6layers:0.05mm (2mil) max.
		8layers:0.07mm (3mil) max.
	Min. spacing between board outline to circuitry pattern of an inner-layer	0.10mm (4mil)
Impedance control		Typical: 50Ω+/-10%